503079465 11/30/2014

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT3126069

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Chun-Hung Chen	11/27/2014
Chien-Li Kuo	11/27/2014
Ming-Tse Lin	11/27/2014

RECEIVING PARTY DATA

Name:	UNITED MICROELECTRONICS CORP.
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park
City:	Hsin-Chu City
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14556215

CORRESPONDENCE DATA

Fax Number: (703)997-4517

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using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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Address Line 4: MERRIFIELD, VIRGINIA 22116

ATTORNEY DOCKET NUMBER:	NAUP2353USA
NAME OF SUBMITTER:	KATE YEH
SIGNATURE:	/KATE YEH/
DATE SIGNED:	11/30/2014

Total Attachments: 6

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PATENT

REEL: 034282 FRAME: 0390

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention:

THROUGH-SUBSTRATE STRUCTURE AND MEHTOD FOR FABRICATING THE SAME

As the below named inventor, I here This declaration is directed to:	by declare that:	
☑ The attached application, or		
☐ United States application nu	ımberfiled o	on , or
☐ PCT international applicatio	n number file	ed on
The above-identified application was	made or authorized to be made by me.	
I believe that I am the original invent application.	or or an original joint inventor of a claime	d invention in the
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	I false statement made in this declaration isonment of not more than five (5) years,	n is punishable or both.
In consideration of the payment by	UNITED MICROELECTRONICS CORP.	having a postal address of
No.3, Li-Hsin Road 2, Science	-Based Industrial Park, Hsin-Chu	– ı City 300, Taiwan, R.O.C
I hereby sell, assign and transfer to a the entire right, title and interest in an invention as above-identified application or invention by the above application or	ol of the sum of One Dollar (\$ 1.00), the divaluable consideration. ASSIGNEE and the successors and assigned to any and all improvements which are tion and, in and to, all Letters Patent to be any continuations, continuation-in-part, and as to Letters Patent any reissue or re-	gnees of the ASSIGNEE e disclosed in the e obtained for said divisions, renewals.
I hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or encumbrance has n this assignment;	been or will be made or
and documents relating to said inven- known and accessible to I and will te	ill, upon its request, be provided promptly tion and said Letters Patent and legal ed stify as to the same in any interference, I cute and deliver to ASSIGNEE or its lega	uivalents as may be itigation proceeding
maintain, issue and enforce said app	nstruments or affidavits required to apply lication, said invention and said Letters F cessary or desirable to carry out the propereunto set hand and seal this NOV	Patent and said
Note: An application data sheet (PTC inventive entity, must accompany this	D/SB/14 or equivalent), including naming s form. Use this form for <u>each additional</u>	the entire

Page 1 of 6

NPO#NAU-P2353-USA:0 CUST#UMCD-2014-0405

Docket No NAUP2353USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor:

Chun-Hung Chen

Date:

NOV 2 7 2014

Signature:

Chun-Hung Chen

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2 of 6 F#NPO-P0002E-US1201 DSC0-103U008694

NPO#NAU-P2353-USA:0

CUST#UMCD-2014-0405

PATENT REEL: 034282 FRAME: 0392

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

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☑ The attached application, or	
☐ United States application num	berfiled on, or
☐ PCT international application r	numberfiled on
The above-identified application was m	ade or authorized to be made by me.
I believe that I am the original inventor application.	or an original joint inventor of a claimed invention in the
	lse statement made in this declaration is punishable nment of not more than five (5) years, or both.
	NITED MICROELECTRONICS having a postal address of ORP.
No.3, Li-Hsin Road 2, Science-B	ased Industrial Park, Hsin-Chu City 300, Taiwan, R.O.C
(referred to as "ASSIGNEE"below) to I acknowledged, andfor other good and v	of the sum of One Dollar (\$ 1.00), the receipt of which is hereby aluable consideration.
the entire right, title and interest in and invention as above-identified application invention by the above application or ar	SIGNEE and the successors and assignees of the ASSIGNEE to any and all improvements which are disclosed in the n and, in and to, all Letters Patent to be obtained for said by continuations, continuation-in-part, divisions, renewals, as to Letters Patent any reissue or re-examination thereof.
I hereby covenant that no assignment, entered into which would conflict with the	sale, agreement or encumbrance has been or will be made or iis assignment;
and documents relating to said inventio	upon its request, be provided promptly with all pertinent facts in and said Letters Patent and legal equivalents as may be by as to the same in any interference, litigation proceeding e and deliver to ASSIGNEE or its legal
maintain, issue and enforce said application	ruments or affidavits required to apply for, obtain, ation, said invention and said Letters Patent and said said said sarry or desirable to carry out the proposes thereof. Sunto set hand and seal this NOV 2 7 2014 (Date of signing
	B/14 or equivalent), including naming the entire orm. Use this form for each additional inventor.

Page 3 of 6

NPO#NAU-P2353-USA:0 CUST#UMCD-2014-0405

Docket No NAUP2353USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor:

Chien-Li Kuo

Date:

NOV 2 7 2014

Signature:

Page 4 of

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

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THROUGH-SUBSTRATE STRUCTURE AND MEHTOD FOR FABRICATING THE SAME

As the below named inventor, I hereby declare that: This declaration is directed to:
☑ The attached application, or
☐ United States application numberfiled on, or
☐ PCT international application numberfiled on
The above-identified application was made or authorized to be made by me.
I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.
I hereby acknowledge that any willful false statement made in this declaration is punishable under18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.
In consideration of the payment by UNITED MICROELECTRONICS having a postal address of CORP.
No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu City 300, Taiwan, R.O.
(referred to as "ASSIGNEE"below) to I of the sum of One Dollar (\$ 1.00), the receipt of which is hereby acknowledged, andfor other good and valuable consideration.
I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.
I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal
representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof. IN WINTNESS WHEREOF, I have hereunto set hand and seal this NOV & 7 2014 (Date of signir
Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire

Page 5 of 6

NPO#NAU-P2353-USA:0 CUST#UMCD-2014-0405

Docket No NAUP2353USA

Inventor: Ming-Tse Lin Date: NOV 2 7 2014

signature: Ming-Tse Line

NPO#NAU-P2353-USA:0 CUST#UMCD-2014-0405

RECORDED: 11/30/2014

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F#NPO-P0002E-US1201 DSC0-103U008694

PATENT REEL: 034282 FRAME: 0396